

Title (en)
METHOD FOR JOINING ALIGNED DISCRETE OPTICAL ELEMENTS

Title (de)
VERFAHREN ZUM FÜGEN JUSTIERTER DISKRETER OPTISCHER ELEMENTE

Title (fr)
PROCÉDÉ POUR JOINDRE DES ÉLÉMENTS OPTIQUES DISCRETS AJUSTÉS

Publication
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Application
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Priority

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Abstract (en)
[origin: WO2008083676A1] The invention relates to a method for joining aligned discrete optical elements. The object of the invention is to provide a method by means of which the optical elements can be joined in the aligned state, wherein a thermal connection having long-term stability can be produced at little expense and with high positioning accuracy. Surface regions to be joined to the optical element can be provided with at least one thin metallic layer by means of the method according to the invention for joining aligned discrete optical elements, wherein the regions are subsequently wetted using a liquid solder in a contactless dosed manner. The solder that is free of flux is applied to the surface regions to be joined via a nozzle using a pressurized gas stream.

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Citation (examination)

- US 2006219760 A1 20061005 - WAGOH TATSUYA [JP], et al
- US 2006237514 A1 20061026 - WAGOU TATSUYA [JP], et al
- US 3648915 A 19720314 - LEIBFRIED WOLFGANG, et al

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